TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20µs) - See Figure 1	P_{PP}	250	Watts
Operating Temperature	T_A	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER (Note 1 -2)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ IP = 1A V_C VOLTS	MAXIMUM LEAKAGE CURRENT @V_{WM} I_D µA	TYPICAL CAPACITANCE @0V, 1MHz C pF
GBLC03I	C	3.0	4.0	7.0	5	0.6
GBLC03CI	CC	3.0	4.0	7.0	5	0.6
GBLC05I	A	5.0	6.0	9.8	5	0.6
GBLC05CI	AC	5.0	6.0	9.8	5	0.6
GBLC08I	B	8.0	8.5	13.4	2	0.6
GBLC08CI	BC	8.0	8.5	13.4	2	0.6
GBLC12I	D	12.0	13.3	19.0	1	0.6
GBLC12CI	DC	12.0	13.3	19.0	1	0.6
GBLC15I	E	15.0	16.7	24.0	1	0.6
GBLC15CI	EC	15.0	16.7	24.0	1	0.6
GBLC18I	F	18.0	20.0	29.0	1	0.6
GBLC18CI	FC	18.0	20.0	29.0	1	0.6
GBLC24I	H	24.0	26.7	43.0	1	0.6
GBLC24CI	HC	24.0	26.7	43.0	1	0.6

NOTES
1. Part numbers with an additional "C" suffix are bidirectional devices, i.e., GBLC05**C**I.
2. Unidirectional Only: Positive potential is applied from pin 1 to 2.

TYPICAL DEVICE CHARACTERISTICS

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

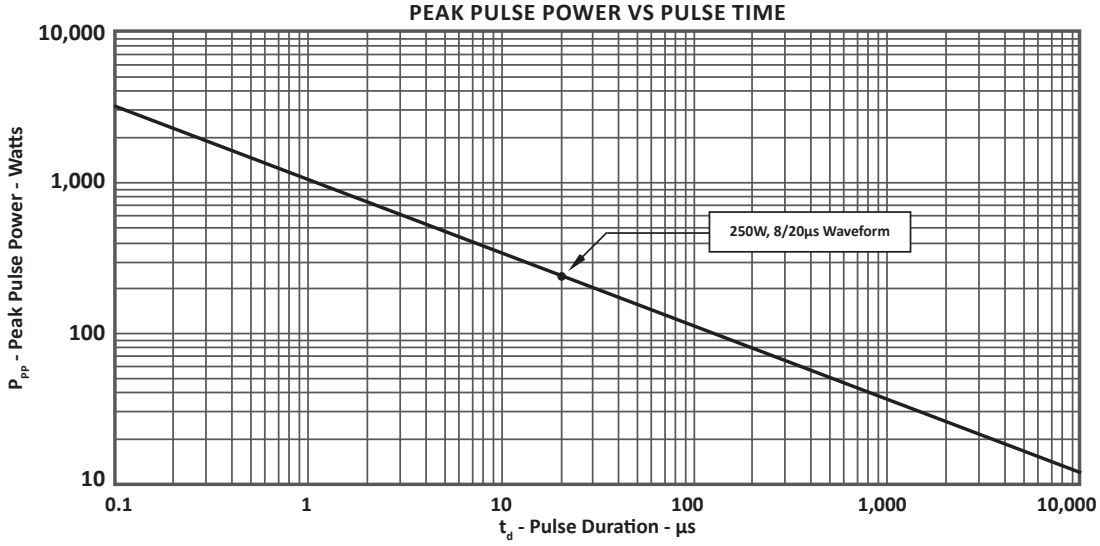
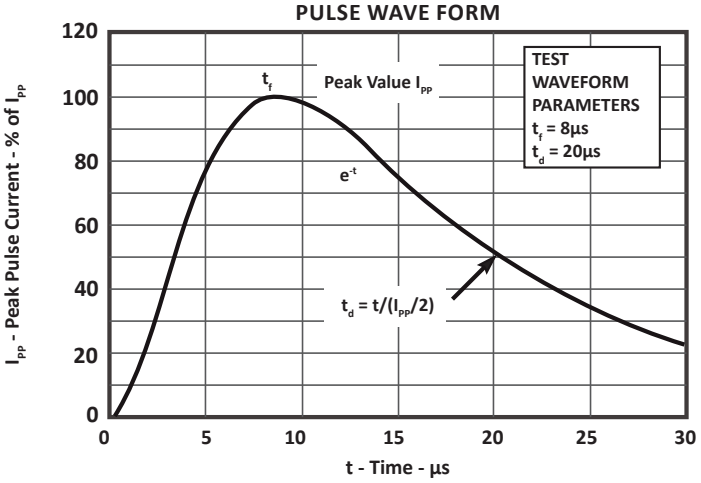
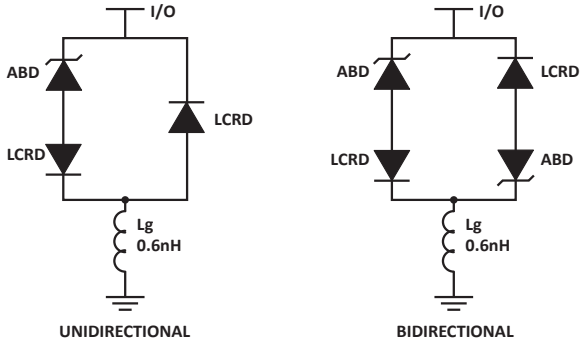


FIGURE 2
PULSE WAVE FORM



SPICE MODEL

FIGURE 1
SPICE MODEL



ABD - Avalanche Breakdown Diode (TVS)
LCRD: Low Capacitance Rectifier Diode
Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS

PARAMETER	UNIT	ABD(TVS)	LCRD
BV	V	See Table 2	100
IBV	µA	1	0.5
C_{jo}	pF	See Table 2	0.3
I_S	A	See Table 2	1E-11
Vj	V	0.6	0.6
M	-	0.33	0.33
N	-	1	1
R_S	Ohms	See Table 2	0.75
TT	s	1E-8	1E-9
EG	eV	1.11	1.11

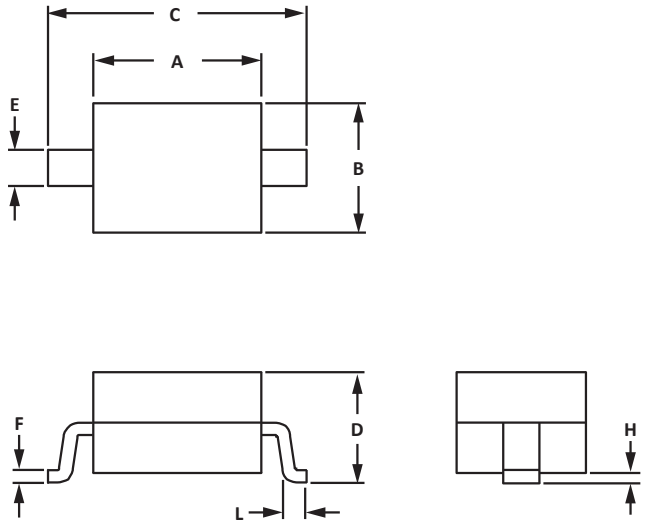
TABLE 2 - ABD SPECIFIC SPICE PARAMETERS

PART NUMBER	B_V(VOLTS)	C_{jo}(pF)	I_S (AMPS)	Rs(OHMS)
GBLC03I	4.0	200	1E-11	0.22
GBLC05I	6.0	140	1E-11	0.18
GBLC08I	8.5	67	1E-11	0.12
GBLC12I	13.3	55	1E-13	1.10
GBLC15I	16.7	47	1E-13	1.43
GBLC18I	20.0	40	1E-13	2.30
GBLC24I	26.7	28	1E-13	4.24
GBLC03CI	4.0	200	1E-11	0.22
GBLC05CI	6.0	140	1E-11	0.18
GBLC08CI	8.5	67	1E-11	0.12
GBLC12CI	13.3	55	1E-13	1.10
GBLC15CI	16.7	47	1E-13	1.43
GBLC18CI	20.0	40	1E-13	2.3
GBLC24CI	26.7	28	1E-13	4.24

SOD-323 PACKAGE INFORMATION

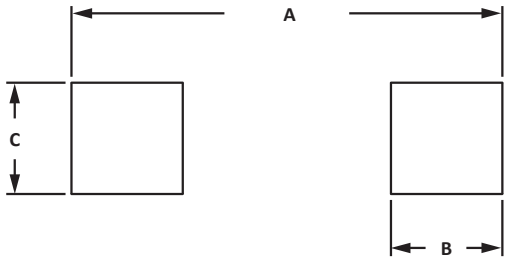
OUTLINE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.60	1.90	0.063	0.075
B	1.15	1.45	0.045	0.057
C	2.39	2.70	0.094	0.106
D	0.80	1.10	0.031	0.043
E	0.25	0.40	0.010	0.016
F	0.10	0.20	0.004	0.008
H	-	0.10	-	0.004
L	0.20	-	0.008	-

NOTES
1. Controlling dimension: millimeters.
2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
3. Dimensions are exclusive of mold flash and metal burrs.

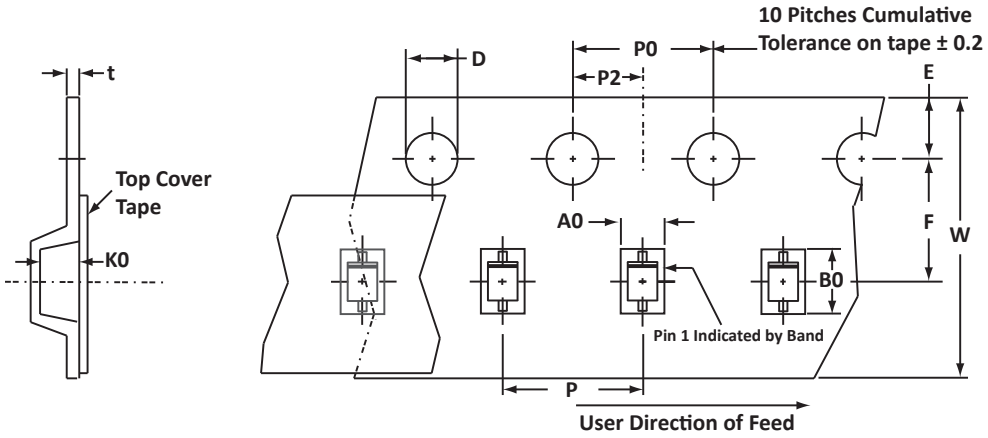


PAD LAYOUT DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.87	3.12	0.113	0.123
B	0.66	0.91	0.026	0.036
C	0.66	0.91	0.026	0.036

NOTES
1. Controlling dimension: millimeters.



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	8mm	1.55 ± 0.10	2.90 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES
1. Dimensions are in millimeters.
2. Surface mount product is taped and reeled in accordance with EIA-481.
3. Suffix - T7 = 7" Reel - 3,000 pieces per 8mm tape.
4. Marking on Part - marking code (see page 2), polarity band (Unidirectional Only).

ORDERING INFORMATION					
BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
GBLCxxI/GBLCxxCI	-LF	-T7	3,000	7"	n/a
This device is only available in a Lead-Free configuration.					

COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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